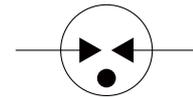


FEATURES

- | Surface Mounting Design 8.0*6.0mm
- | High Current Handling Capability 10,000A @ 8/20 μs
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



8.0*6.0mm



Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	800-1200	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤ 1600	V
	At 1kV/μs	Typical values of distribution ≤ 1500	V
Impulse Discharge Current 2)	8/20μs	10	KA
AC Discharge Current	50Hz, 1S, 10times	10	A
Insulation Resistance	DC=100V	≥ 1	GΩ
Capacitance at 1MHz	V _{DC} =0.5V	≤ 1	pF
Operating and Storage Temperature		-40-125	°C

1) In ionized mode

2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

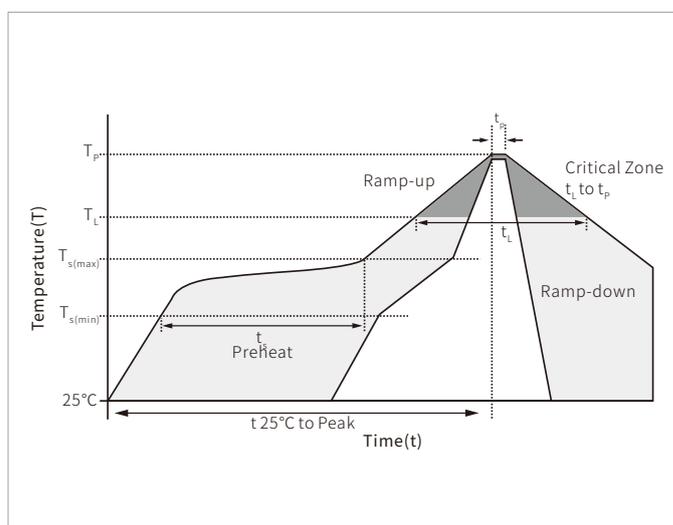
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time

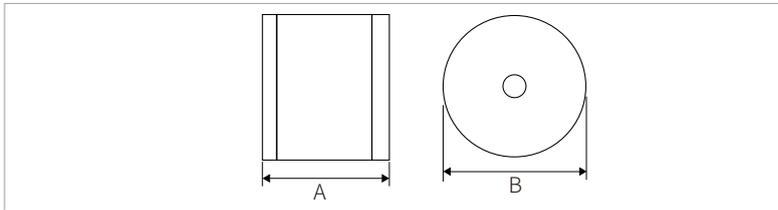
NOTE: Up-screen program can be specified by customer' s request via contacting Semiware service

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T _L) to peak T _{s(max)} to T _L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T _L) (Liquidus)	217°C
	Time(min to max)(t _s)	60 – 150 seconds
Peak Temperature (T _p)		260 °C
Time within 5°C of actual peak Temperature (t _p)		20-40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T _p)		8 minutes max.
Do not exceed		260°C



DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	mm
A	6.0+0.3/-0.5
B	8.0+0.3/-0.5

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2R08B1000B	8.0*6.0mm	 SG1000 08	100pcs	Box

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Minhang Shanghai China
201000

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By QR Code

Website



Wechat

To find your local partner within Semiware' s global website: www.semiware.com

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